

October 2014

KSC2328A NPN Epitaxial Silicon Transistor

Features

- Audio Power Amplifier Application
- · Complement to KSA928A
- 3 W Output Application



Ordering Information

| Part Number | Top Mark | Package | Packing Method |
|-------------|-----------|----------|----------------|
| KSC2328AOTA | C2328A O- | TO-92 3L | Ammo |
| KSC2328AYBU | C2328A Y- | TO-92 3L | Bulk |
| KSC2328AYTA | C2328A Y- | TO-92 3L | Ammo |

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}\text{C}$ unless otherwise noted.

| Symbol | Parameter | Value | Unit | |
|------------------|---------------------------|-------------|------|--|
| V _{CBO} | Collector-Base Voltage | 30 | V | |
| V_{CEO} | Collector-Emitter Voltage | 30 | V | |
| V _{EBO} | Emitter-Base Voltage | 5 | V | |
| I _C | Collector Current | 2 | Α | |
| TJ | Junction Temperature | 150 | °C | |
| T _{STG} | Storage Temperature | -55 to +150 | °C | |

Thermal Characteristics(1)

Values are at $T_A = 25$ °C unless otherwise noted.

| Symbol | Parameter | Value | Unit |
|-----------------|---|-------|-------|
| D | Power Dissipation | 1000 | mW |
| P_{D} | Derate Above 25°C | 8.0 | mW/°C |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 125 | °C/W |

Note:

1. PCB size: FR-4, 76 mm x 114 mm x 1.57 mm (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|-----------------------|--------------------------------------|--|------|------|------|------|
| BV _{CBO} | Collector-Base Breakdown Voltage | $I_C = 100 \mu A, I_E = 0$ | 30 | | | V |
| BV _{CEO} | Collector-Emitter Breakdown Voltage | $I_C = 10 \text{ mA}, I_B = 0$ | 30 | | | V |
| BV _{EBO} | Emitter-Base Breakdown Voltage | $I_E = 1 \text{ mA}, I_C = 0$ | 5 | | | V |
| I _{CBO} | Collector Cut-Off Current | $V_{CB} = 30 \text{ V}, I_{E} = 0$ | | | 100 | nA |
| I _{EBO} | Emitter Cut-Off Current | $V_{EB} = 5 \text{ V}, I_{C} = 0$ | | \ | 100 | nA |
| h _{FE} | DC Current Gain | $V_{CE} = 2 \text{ V}, I_{C} = 500 \text{ mA}$ | 100 | | 320 | |
| V _{BE} (on) | Base-Emitter On Voltage | $V_{CE} = 2 \text{ V}, I_{C} = 500 \text{ mA}$ | | | 1.0 | V |
| V _{CE} (sat) | Collector-Emitter Saturation Voltage | $I_C = 1.5 \text{ A}, I_B = 0.03 \text{ A}$ | | | 2.0 | V |
| f _T | Current Gain Bandwidth Product | $V_{CE} = 2 \text{ V}, I_{C} = 500 \text{ mA}$ | | 120 | | MHz |
| C _{ob} | Collector Output Capacitance | $V_{CB} = 10 \text{ V}, I_{E} = 0,$ f = 1 MHz | | 30 | | pF |

h_{FE} Classification

| Classification | 0 | Y | | |
|-----------------|-----------|-----------|--|--|
| h _{FE} | 100 ~ 200 | 160 ~ 320 | | |

Typical Performance Characteristics

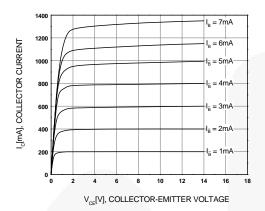


Figure 1. Static Characteristic

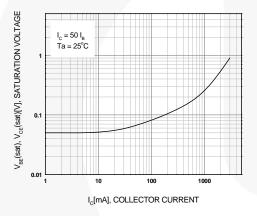


Figure 3. Collector-Emitter Saturation Voltage

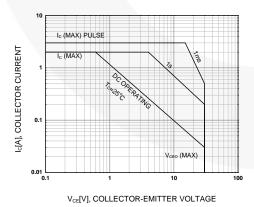


Figure 5. Safe Operating Area

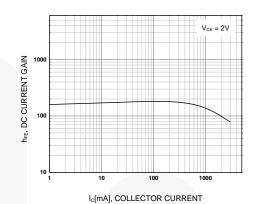


Figure 2. DC Current Gain

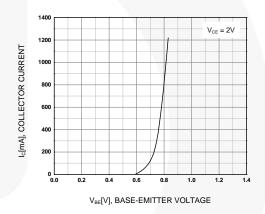


Figure 4. Base-Emitter On Voltage

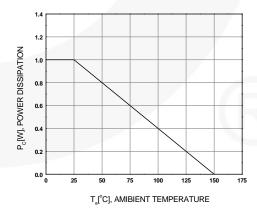
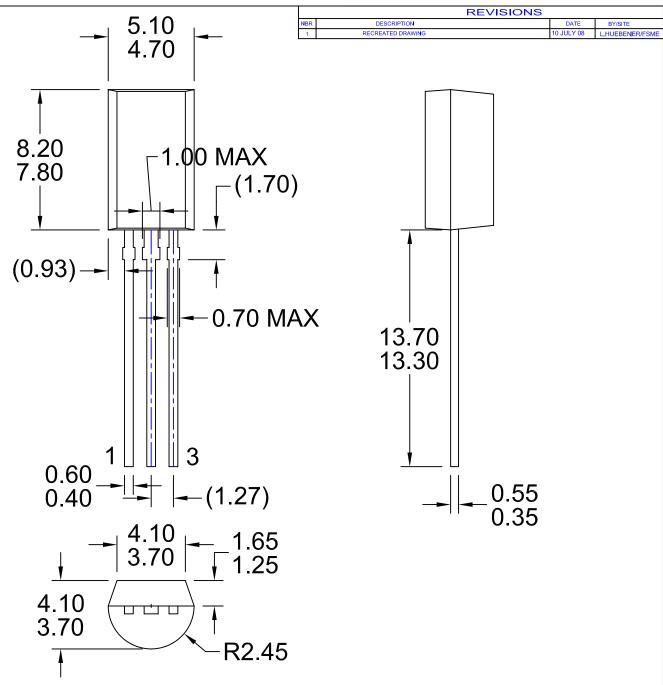


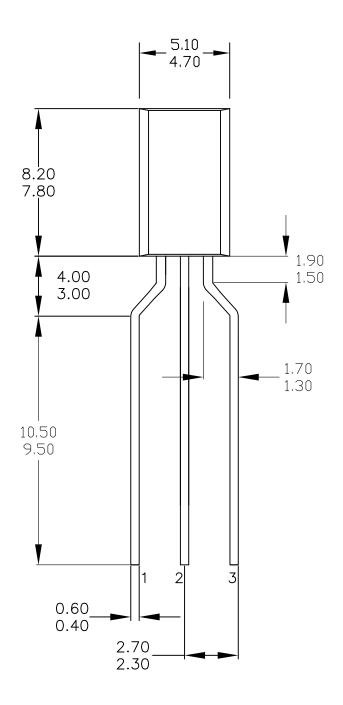
Figure 6. Power Derating

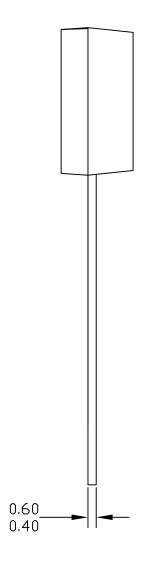


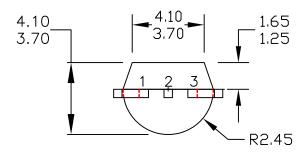
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